



TotalEnergies

Refining & Chemicals
Polymers

Description

Polypropylene Aceso® PPM R021 is random copolymer polypropylene with a Melt Flow Index of 1.8 g/10 min specially developed for the extrusion blow-moulding of medical containers and medical devices, to the exclusion of implants. This grade can also be injection moulded.

Characteristics

	Method	Unit	Typical Value
Rheological properties			
Melt Flow Index 230°C/2.16 kg	ISO 1133	g/10 min	1.8
Mechanical properties			
Tensile Strength at Yield	ISO 527-2	MPa	26
Elongation at Yield	ISO 527-2	%	10
Tensile modulus	ISO 527-2	MPa	1000
Flexural modulus	ISO 178	MPa	900
Izod Impact Strength (notched) at 23°C	ISO 180	kJ/m ²	6
Charpy Impact Strength (notched) at 23°C	ISO 179	kJ/m ²	8
Hardness Rockwell - R-scale	ISO 2039-2		82
Thermal properties			
Melting Point	ISO 3146	°C	149
Vicat Softening Point	ISO 306	°C	
50N-50°C per hour			67
10N-50°C per hour			130
Other physical properties			
Density	ISO 1183	g/cm ³	0.902
Bulk Density	ISO 1183	g/cm ³	0.525

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: www.polymers.totalenergies.com.

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